

DERWENT ABSTRACT FOR: JP 09-316322 (Asahi), published 9 Dec 1997:

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ACCESSION NUMBER: 1998-082841 [08] WPIINDEX

DOC. NO. CPI: C1998-028047

TITLE: Polyphenylene ether-based resin moulding - consisting of hydrogenated vinyl aromatic compound-conjugated diene compound copolymer dispersed in polyolefin.

DERWENT CLASS:

A18 A25

PATENT ASSIGNEE(S): (ASAHI) ASAHI KASEI KOGYO KK

COUNTRY COUNT:

1

PATENT INFORMATION:

PATENT NO	KIND	DATE	WEEK	LA	PG
JP 09316322	A	19971209 (199808)*		19	<--

APPLICATION DETAILS:

PATENT NO	KIND	APPLICATION	DATE
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The polyolefin has: (a) a continuous phase, a homogeneous phase consisting of polyphenylene ether, or polyphenylene ether and a styrene-based resin; and (b) a dispersed phase dispersed with substantially a breadth dia. of 0.6 microns or below. The hydrogenated material of a vinyl aromatic compound-conjugated diene compound copolymer is dispersed with substantially a breadth dia. of 0.01 microns or more and 0.3 microns or below in the polyolefin. The vinyl aromatic compound-conjugated diene compound copolymer is coagulated in the outer layer of the mixed phase of the polyolefin and the hydrogenated material of the vinyl aromatic compound-conjugated diene compound copolymer. The single vinyl aromatic compound-conjugated diene compound copolymer is dispersed with substantially a breadth dia. of 0.3 microns or below. Also claimed is that a resin composition is used for forming the resin moulding consisting of: (a) 10-88 wt.%-polyphenylene ether; (b) a 0-78 wt.%-styrene-based resin; (c) 3-15 wt.%-polyolefin; (d) at least one 6-20 wt.%-block copolymer consisting of a polymer block (A) consisting mainly of at least one vinyl aromatic compound and a polymer block B consisting mainly of at least one conjugated diene compound, and selected from a block copolymer containing the 30-85 wt.%-vinyl aromatic compound; and (e) a 3-20 wt.% hydrogenated material of at least one block copolymer consisting of a polymer block (A) consisting mainly of at least one vinyl aromatic compound and a polymer block B consisting mainly of at least one conjugated diene compound and selected from a hydrogenated material of a block copolymer containing the 20-50 wt.%-vinyl aromatic compound.

USE - The polyphenylene ether-based resin moulding is used in films, or sheets.

ADVANTAGE - The polyphenylene ether-based resin moulding has superior balanced heat resistance and rigidity, no peeling under severe moulding conditions, superior sliding and impact resistance.

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